

C1206C225K3RECTU

Aliases (C1206C225K3REC7800)

ESD SMD Comm X7R, Ceramic, 2.2 uF, 10%, 25 VDC, X7R, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II, 1206, 1.5 mm



Click [here](#) for the 3D model.

General Information

Series	ESD SMD Comm X7R
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II
Features	Temperature Stable, Class II
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	41 mg
Shelf Life	78 Weeks
MSL	1

Dimensions

Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
T	1.6mm +/-0.20mm
S	1.5mm MIN
B	0.5mm +/-0.25mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2000

Specifications

Capacitance	2.2 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	25 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	3.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	227.3 MOhms

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